



**JOC305XM4 Series**

**DC Input, Random-Phase Photo TRIAC Photo Coupler**

**Description**

The JOC305XM4 series combine an AlGaAs infrared emitting diode as the emitter which is optically coupled to a monolithic silicon random-phase photo triac in a plastic SOP4 package. With the robust coplanar double mold structure, JOC305XM4 series provide the most stable isolation feature.

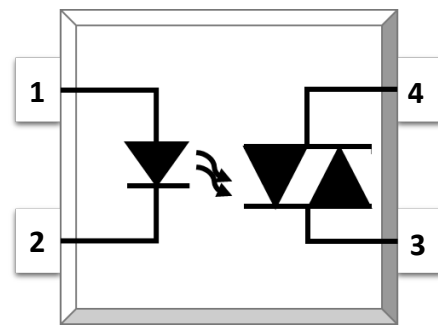
**Features**

- High isolation 3750 VRMS
- DC input with random-phase photo triac output
- Operating temperature range - 40 °C to 100 °C
- REACH & RoHS compliance
- Halogen free
- MSL class 1
- Regulatory Approvals
  - UL
  - VDE
  - CQC

**Applications**

- Solenoid/valve controls
- Lighting controls
- Motor controls
- Temperature controls
- Static AC power switches
- Solid state relays
- Interfacing microprocessors to 115 to 240VAC peripherals

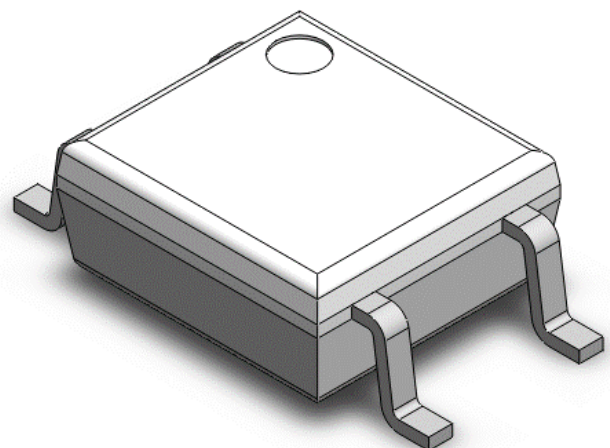
**SCHEMATIC**



**PIN DEFINITION**

- 1. Anode**
- 2. Cathode**
- 3. Terminal**
- 4. Terminal**

**PACKAGE OUTLINE**



### ABSOLUTE MAXIMUM RATINGS

PARAMETER	SYMBOL	VALUE	UNIT	NOTE
INPUT				
Forward Current	$I_F$	60	mA	
Reverse Voltage	$V_R$	6	V	
Junction Temperature	$T_j$	125	°C	
Input Power Dissipation	$P_i$	100	mW	
OUTPUT				
Off-state Output Terminal Voltage	JOC301XM4	250	V	
	JOC302XM4	400		
	JOC305XM4	600		
	JOC307XM4	800		
Peak Repetitive Surge Current PW=100μs, 120pps	$I_{TSM}$	1	A	
On-State RMS Current	$I_{T(RMS)}$	100	mA	
Junction Temperature	$T_j$	125	°C	
Output Power Dissipation	$P_o$	300	mW	
COMMON				
Total Power Dissipation	$P_{tot}$	330	mW	
Isolation Voltage	$V_{iso}$	3750	V <sub>rms</sub>	1
Operating Temperature	$T_{opr}$	-40~100	°C	
Storage Temperature	$T_{stg}$	-55~125	°C	
Soldering Temperature	$T_{sol}$	260	°C	2

Note 1. AC For 1 Minute, R.H. = 40 ~ 60%

Note 2. For 10 seconds

**ELECTRICAL OPTICAL CHARACTERISTICS at Ta=25°C**

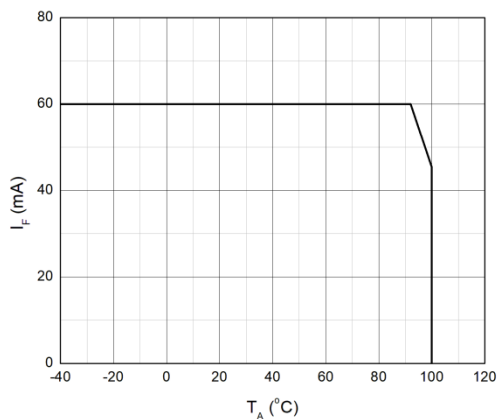
PARAMETER	SYMBOL	MIN.	TYP.	MAX.	UNIT	TEST CONDITION	NOTE
INPUT							
Forward Voltage	$V_F$	-	1.24	1.4	V	$I_F=10\text{mA}$	
Reverse Current	$I_R$	-	-	10	$\mu\text{A}$	$V_R=6\text{V}$	
Input Capacitance	$C_{in}$	-	8.5	250	pF	$V=0, f=1\text{kHz}$	
OUTPUT							
Peak Off-state Current, Either Direction	$I_{DRM}$	-	-	100	nA	$V_{DRM}=\text{Rated } V_{DRM}$ $I_F=0$	3
Peak On-state Current, Either Direction	$V_{TM}$	-	1.58	2.5	V	$I_{TM}=100\text{mA}$	
Critical Rate of Rise of Off-state Voltage	$dV/dt$	1000	-	-	$\text{V}/\mu\text{s}$	$V_{PEAK}=\text{Rated } V_{DRM}$	4
TRANSFER CHARACTERISTICS							
LED Trigger Current	JOC3051M4	$I_{FT}$	-	-	15	mA	Terminal Voltage = 3V $I_{TM}=100\text{mA}$
	JOC3052M4		-	-	10		
	JOC3053M4		-	-	5		
Holding Current	$I_H$	-	257	-	$\mu\text{A}$		
Isolation Resistance	Riso	$10^{12}$	$10^{14}$	-	$\Omega$	DC500V, 40 ~ 60% R.H.	
Floating Capacitance	$C_{IO}$	-	0.4	1	pF	$V=0, f=1\text{MHz}$	

Note3. Test voltage must be applied within  $dV/dt$  rating.

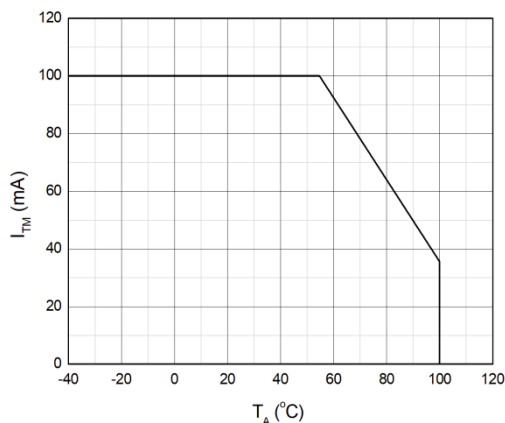
Note4. Refer to Fig.15 & Fig.16

**CHARACTERISTIC CURVES**

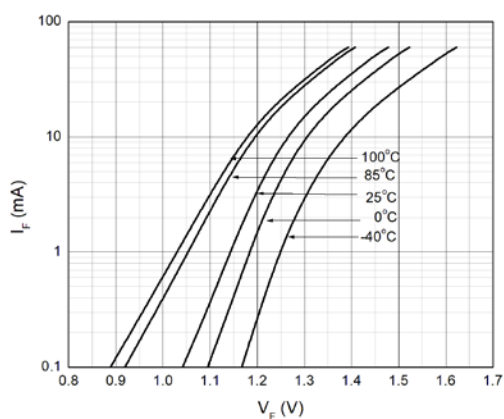
**Fig.1 Forward Current vs. Ambient Temperature**



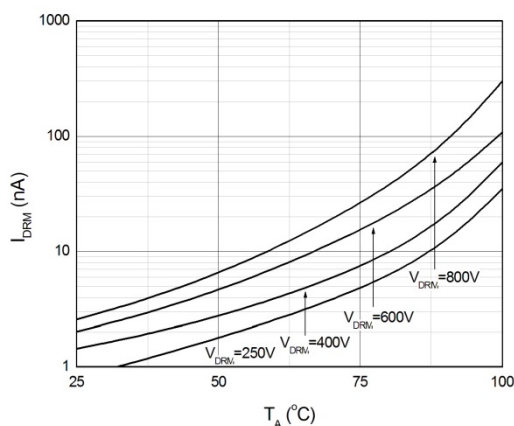
**Fig.2 On-state Terminal Current vs. Ambient Temperature**



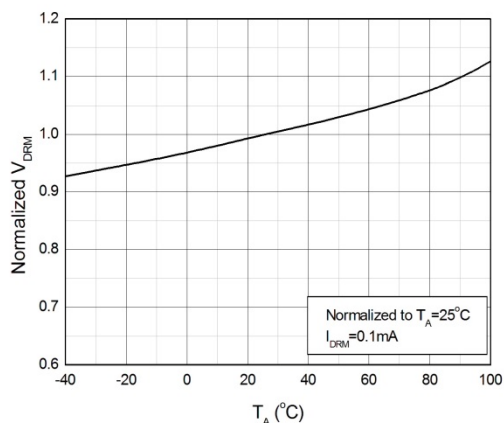
**Fig.3 Forward Current vs. Forward Voltage**



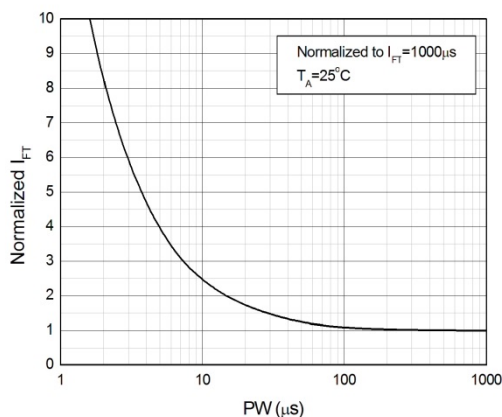
**Fig.4 Off-state Terminal Current vs. Ambient Temperature**



**Fig.5 Normalized Off-state Terminal Voltage vs. Ambient Temperature**

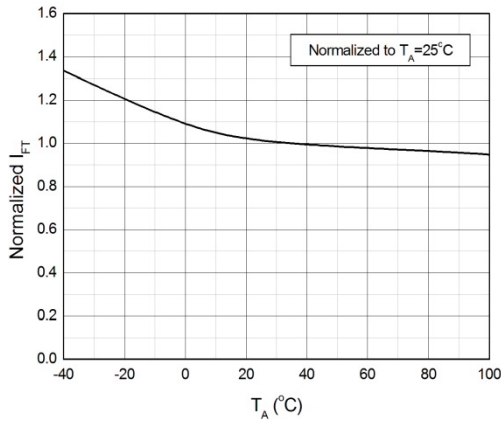


**Fig.6 Normalized Trigger Current vs. LED Trigger Pulse Width**

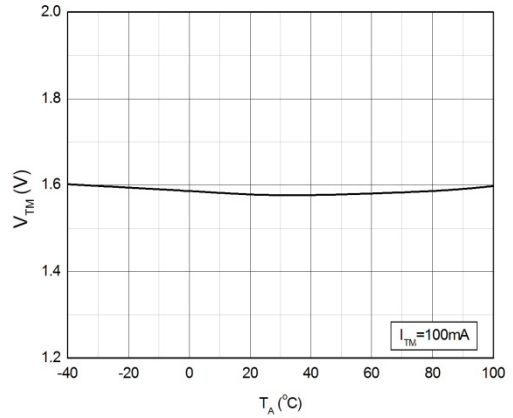


**CHARACTERISTIC CURVES**

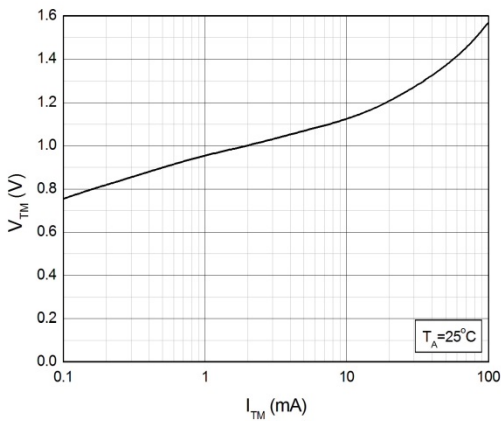
**Fig.7 Normalized Trigger Current vs. Ambient Temperature**



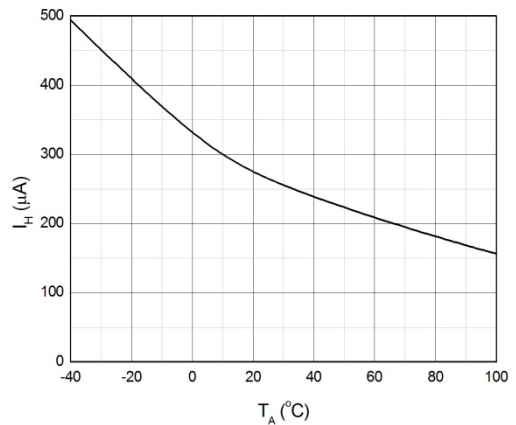
**Fig.8 On-state Terminal Voltage vs. Ambient Temperature**



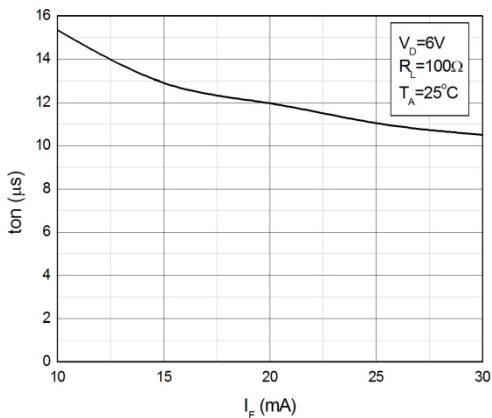
**Fig.9 On-state Terminal Voltage vs. On-state Terminal Current**



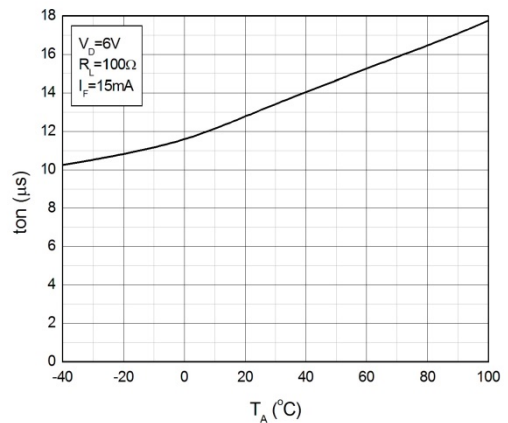
**Fig.10 Holding Current vs. Ambient Temperature**



**Fig.11 Turn On Time vs. Forward Current**

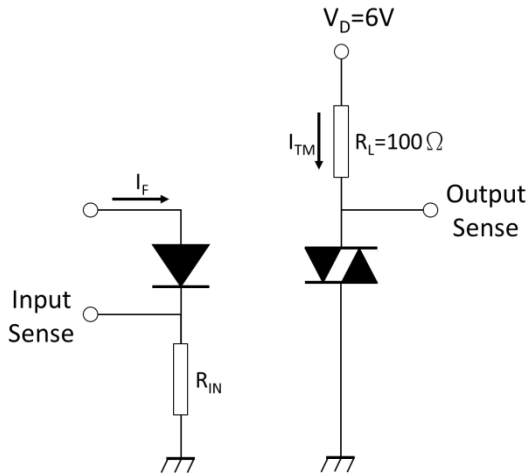


**Fig.12 Turn On Time vs. Ambient Temperature**

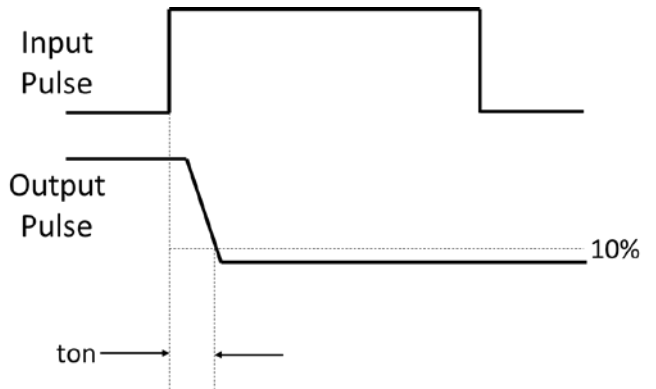


**TEST CIRCUITS**

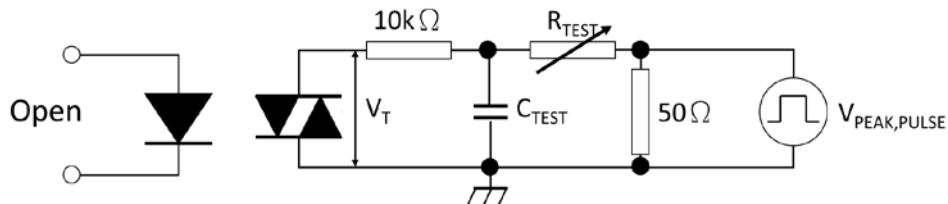
**Fig.13 Test Circuits of Turn On Time**



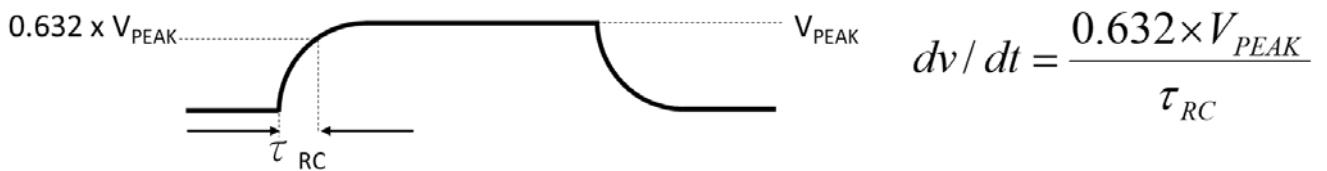
**Fig.14 Waveforms of Turn On Time**



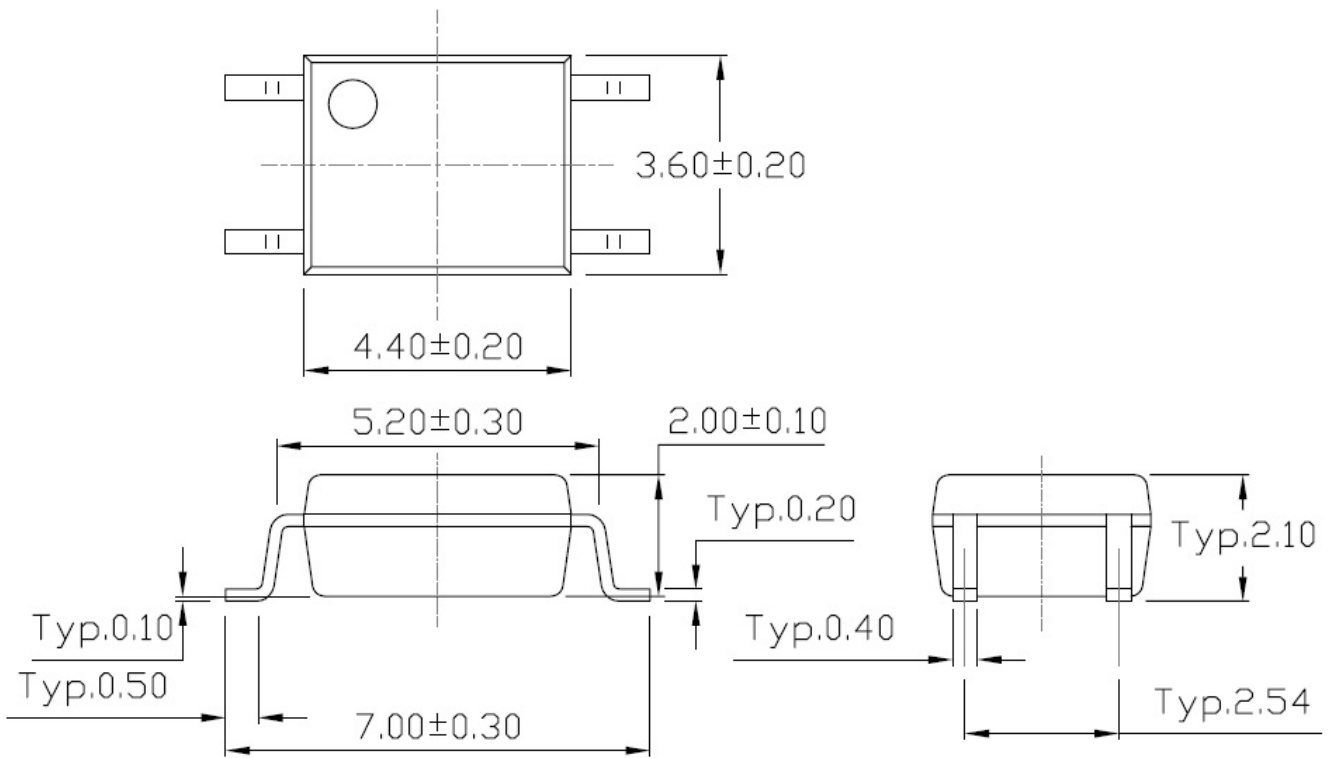
**Fig.15 Test Circuits of dV/dt**



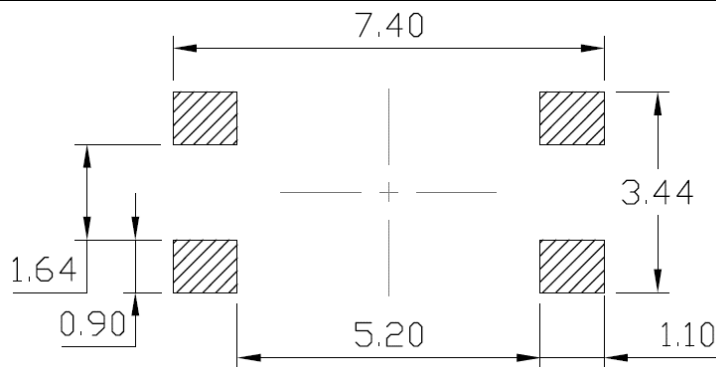
**Fig.16 Waveforms of dV/dt**



**PACKAGE DIMENSIONS** (Dimensions in mm unless otherwise stated)

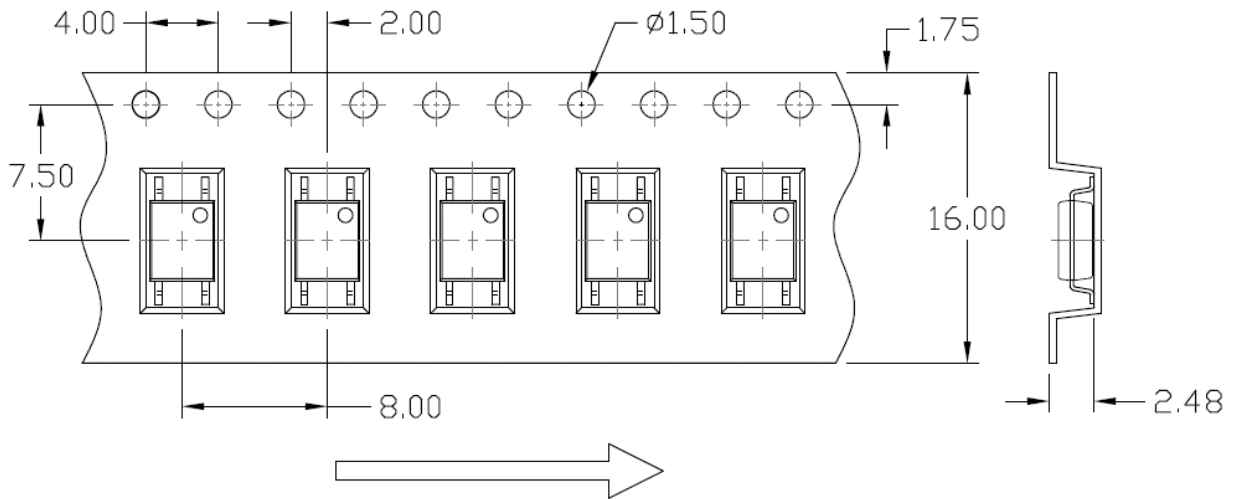


**Recommended Solder Mask** (Dimensions in mm unless otherwise stated)

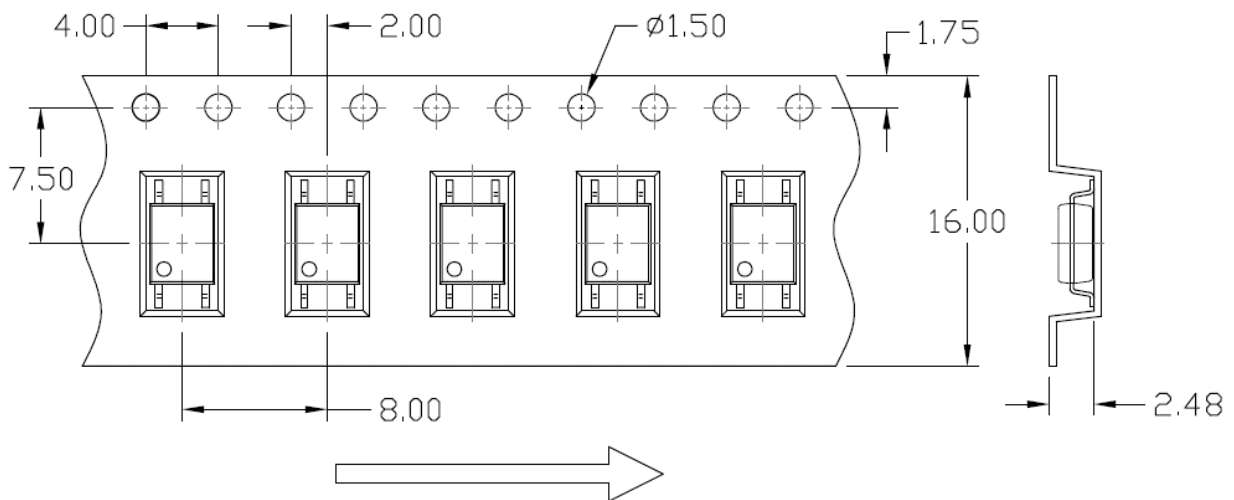


**CARRIER TAPE SPECIFICATIONS (Dimensions in mm unless otherwise stated)**

**Option T1**



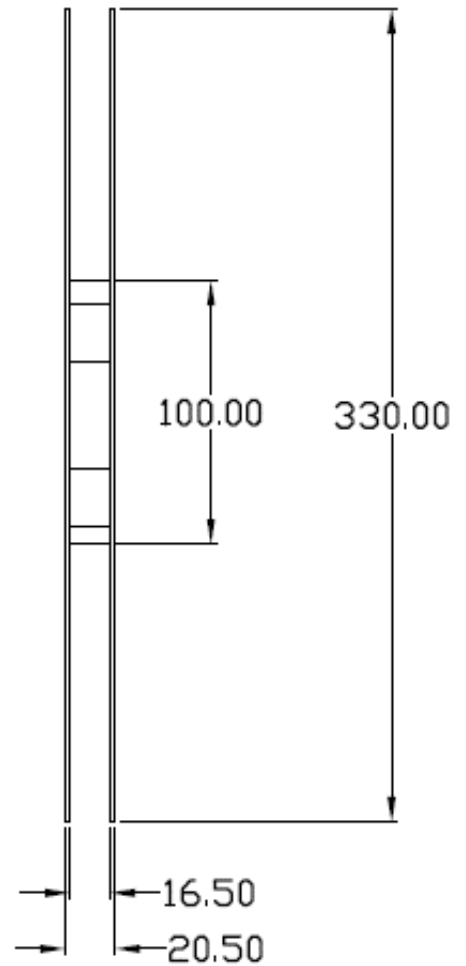
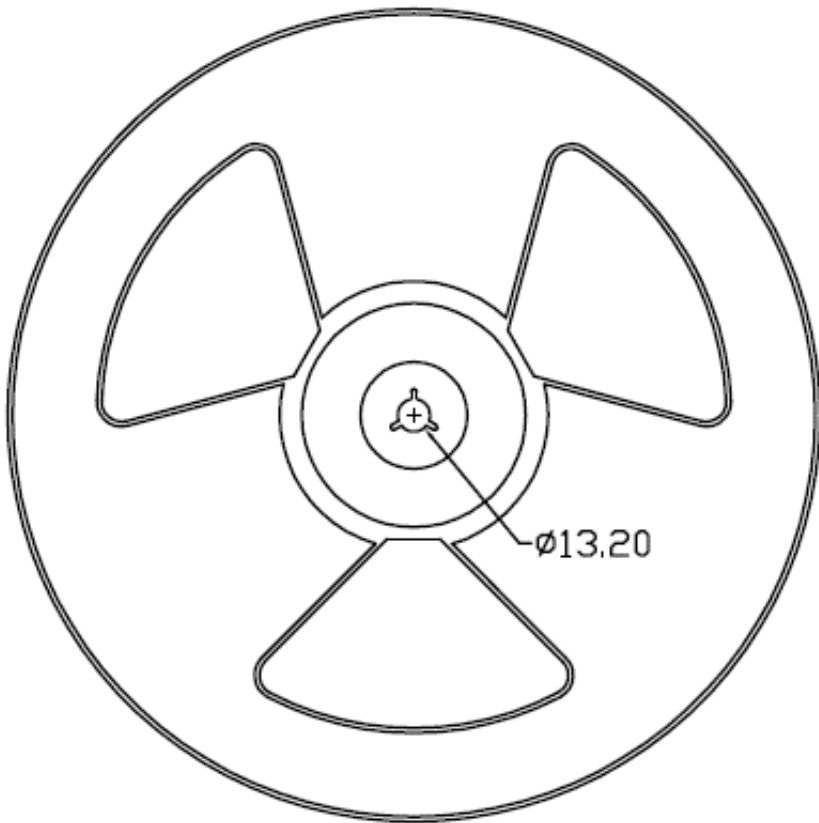
**Option T2**





**REEL SPECIFICATIONS (Dimensions in mm unless otherwise stated)**

**Option T1 & T2**



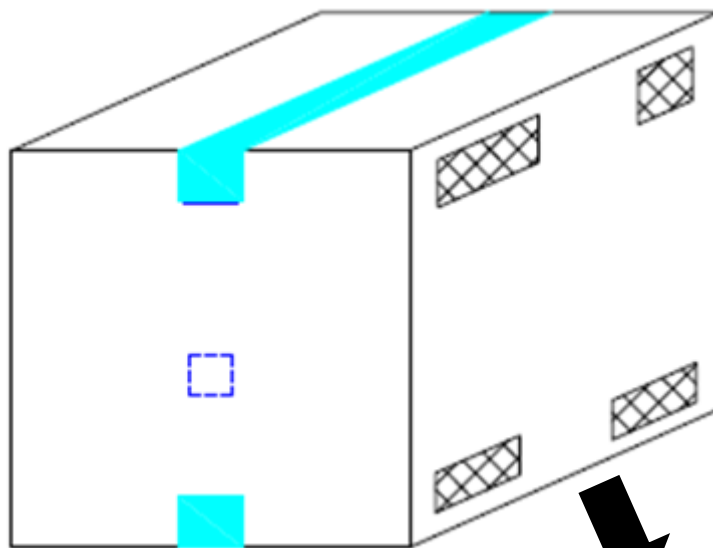
### BOX SPECIFICATIONS (Reel Type)

#### Inner Box

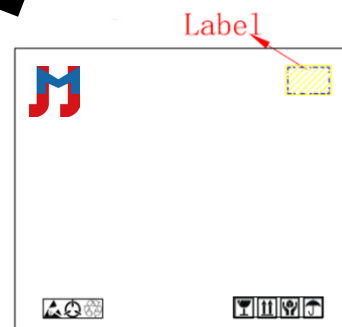


- L x W x H = 36cm x 36cm x 6.9cm

#### Outer Box

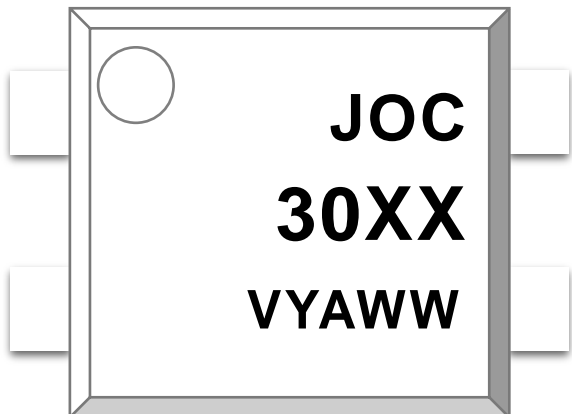


- L x W x H = 45cm x 38cm x 38cm



**ORDERING AND MARKING INFORMATION**

**MARKING INFORMATION**




**JOC** : Company Abbr.  
**30XX** : Part Number & Rank  
**V** : VDE Option  
**Y** : Fiscal Year  
**A** : Manufacturing Code  
**WW** : Work Week

**ORDERING INFORMATION**


**JOC30XXMX(Z)-GV**

**LABEL INFORMATION**

JOC – Company Abbr.  
 30XX – Rank  
 (10/11/12/21/22/23/51/52/53/71/72/73)  
 MX – SOP Package  
 Z – Tape and Reel Option (T1/T2)  
 G – Green  
 V – VDE Option (V or None)

 捷捷微电（深圳）有限公司  
 JIEJIE MICROELECTRONICS (Shenzhen) Co Ltd




Part No : XXXXXXXXXXXXXXXX      Bin Code : X



Lot No : XXXXXXXXXXXX

Date Code : XXXX

Q'ty : XXXX pcs

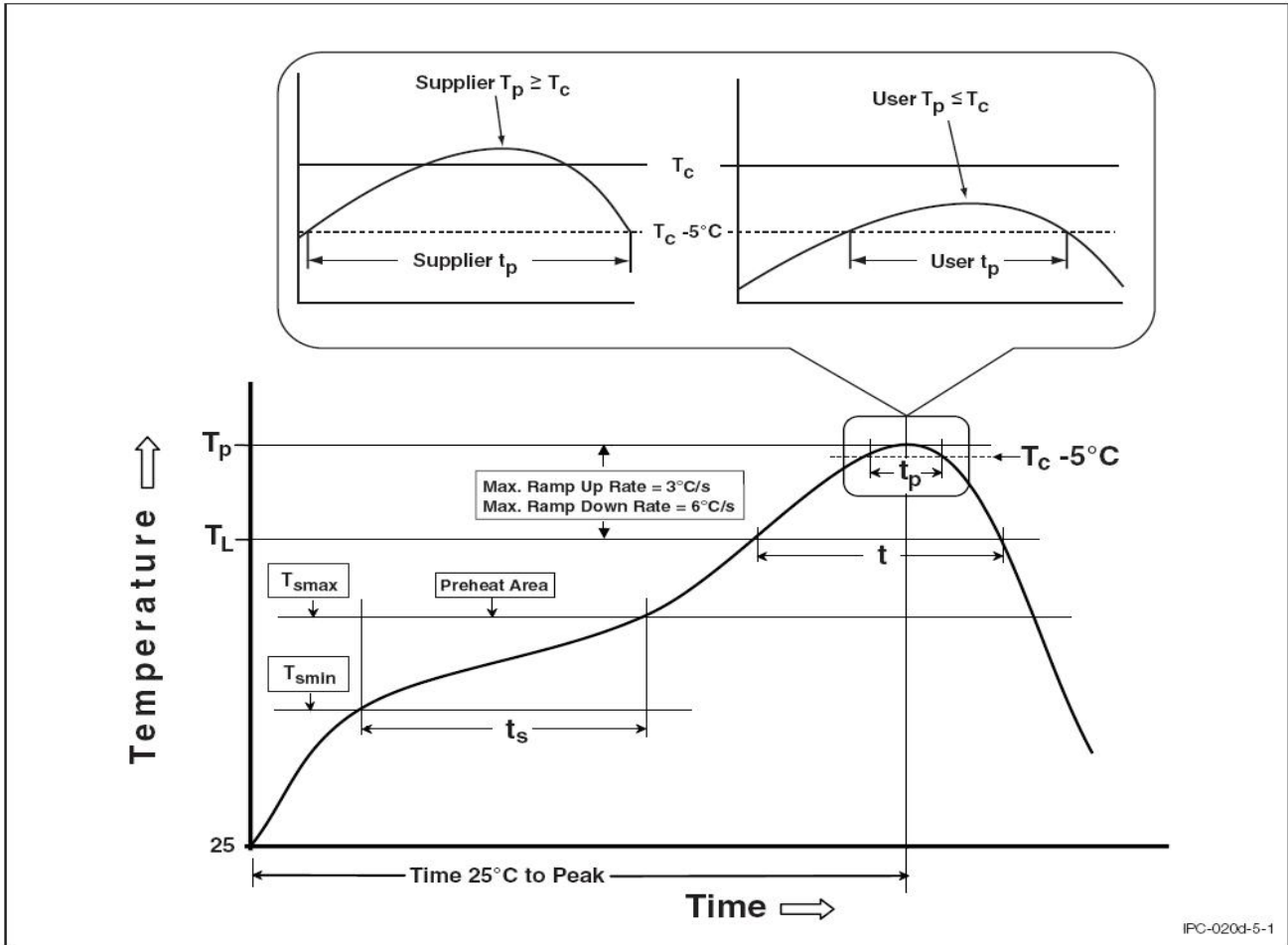




**PACKING QUANTITY**

Option	Quantity	Quantity – Inner box	Quantity – Outer box
T1	3000 Units/Reel	3 Reels/Inner box	5 Inner box/Outer box = 45k Units
T2	3000 Units/Reel	3 Reels/Inner box	5 Inner box/Outer box = 45k Units

**REFLOW INFORMATION**

**REFLOW PROFILE**



IPC-020d-5-1

Profile Feature	Sn-Pb Assembly Profile	Pb-Free Assembly Profile
Temperature Min. ( $T_{smin}$ )	100	150°C
Temperature Max. ( $T_{smax}$ )	150	200°C
Time ( $t_s$ ) from ( $T_{smin}$ to $T_{smax}$ )	60-120 seconds	60-120 seconds
Ramp-up Rate ( $t_L$ to $t_P$ )	3°C/second max.	3°C/second max.
Liquidous Temperature ( $T_L$ )	183°C	217°C
Time ( $t_L$ ) Maintained Above ( $T_L$ )	60 – 150 seconds	60 – 150 seconds
Peak Body Package Temperature	235°C +0°C / -5°C	260°C +0°C / -5°C
Time ( $t_P$ ) within 5°C of 260°C	20 seconds	30 seconds
Ramp-down Rate ( $T_P$ to $T_L$ )	6°C/second max	6°C/second max
Time 25°C to Peak Temperature	6 minutes max.	8 minutes max.

**DISCLAIMER**

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- The products shown in this publication are designed for the general use in electronic applications such as office automation, equipment, communications devices, audio/visual equipment, electrical application and instrumentation purpose, non-infringement and merchantability.
- This product is not intended to be used for military, aircraft, automotive, medical, life sustaining or lifesaving applications or any other application which can result in human injury or death.
- Please contact JIEJIE sales agent for special application request.
- Immerge unit's body in solder paste is not recommended.
- Parameters provided in datasheets may vary in different applications and performance may vary over time. All operating parameters, including typical parameters, must be validated in each customer application by the customer's technical experts. Product specifications do not expand or otherwise modify JIEJIE's terms and conditions of purchase, including but not limited to the warranty expressed therein.
- Discoloration might be occurred on the package surface after soldering, reflow or long-time use. It neither impacts the performance nor reliability.